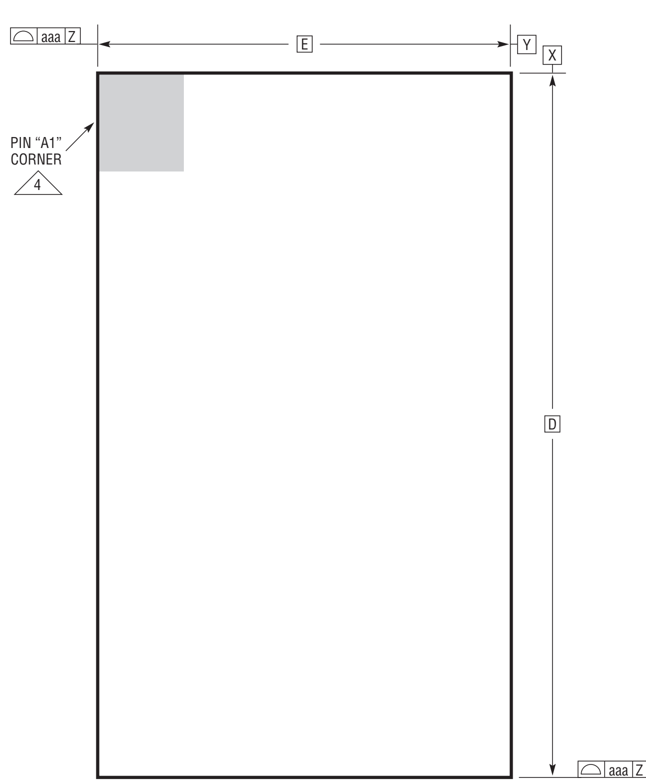
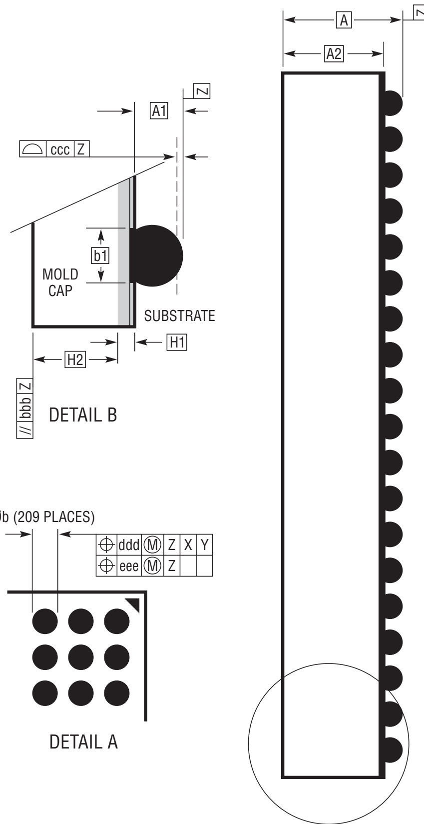
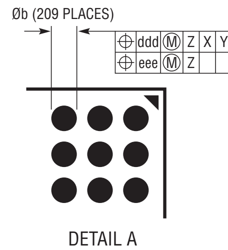
BGA Package
209-Lead (16mm × 9.50mm × 4.72mm)
(Reference LTC DWG# 05-08-1561 Rev A)



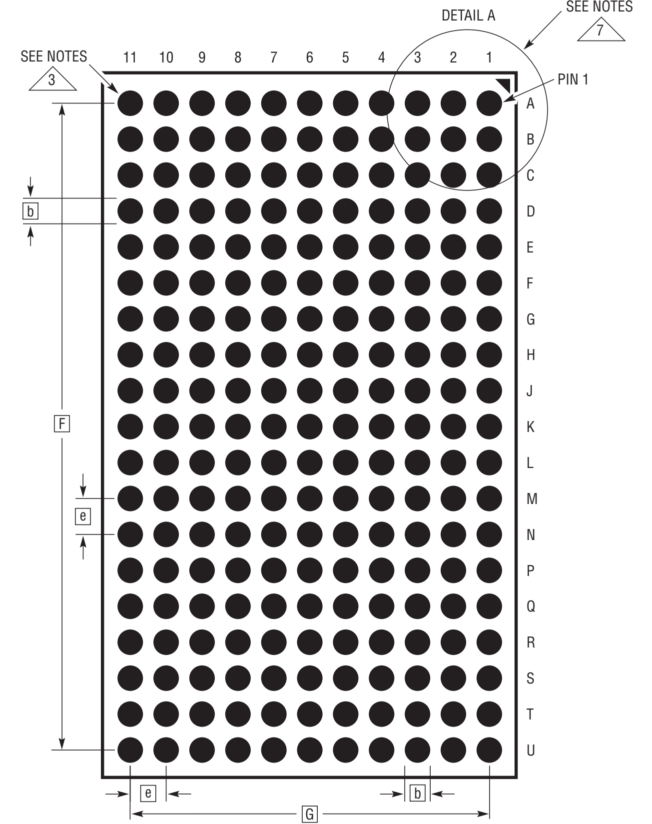
PACKAGE TOP VIEW



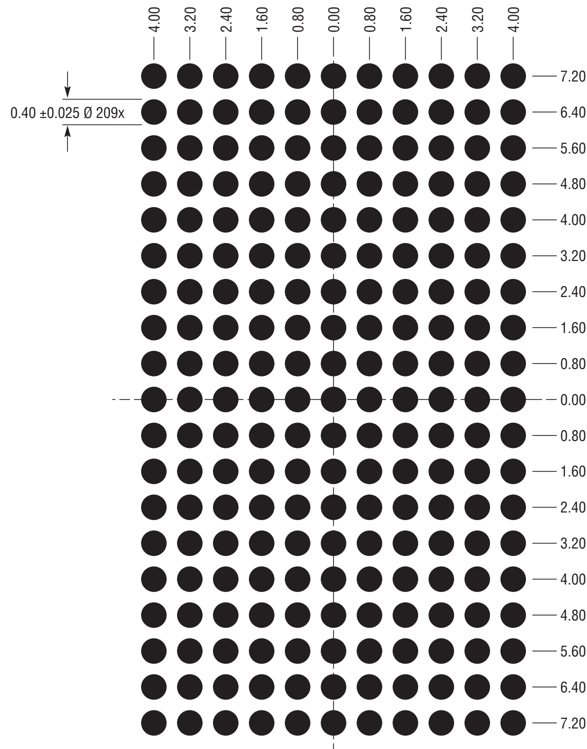
DETAIL B
PACKAGE SIDE VIEW



DETAIL A



PACKAGE BOTTOM VIEW



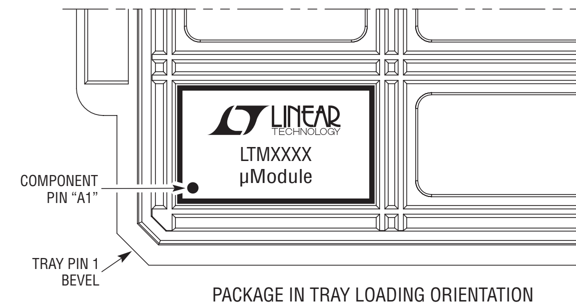
SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTES
A	4.53	4.72	4.91	
A1	0.30	0.40	0.50	BALL HT
A2	4.23	4.32	4.41	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		16.00		
E		9.50		
e		0.80		
F		14.40		
G		8.00		
H1	0.28	0.32	0.36	SUBSTRATE THK
H2	3.95	4.00	4.05	MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 209

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
7. ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 209 1116 REV A